

## **REMARKS**

Claim 1 has been amended to call for providing electrodes in contact with the surface to be polished such that the electrodes and the conductive polishing pad may be coupled to opposite polarity potentials.

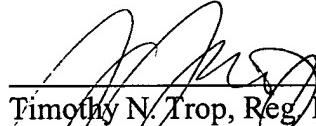
In contrast, the polishing pad 612 in the cited reference is not conductive. It is plainly stated that it is an insulating material. See column 7, lines 45-47. Moreover, there are not regions of opposite polarity (namely, the pad and the electrodes) in contact with the wafer 904 to be polished. The opposite polarity to that provided by the convective pads 903 is supplied by the copper layer 610 which is spaced back from the wafer 904.

Therefore, claim 1 as amended patentably distinguishes over the reference.

On a similar analysis, the dependent claims and the other independent claims also distinguish.

Respectfully submitted,

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